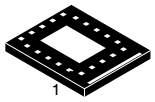
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

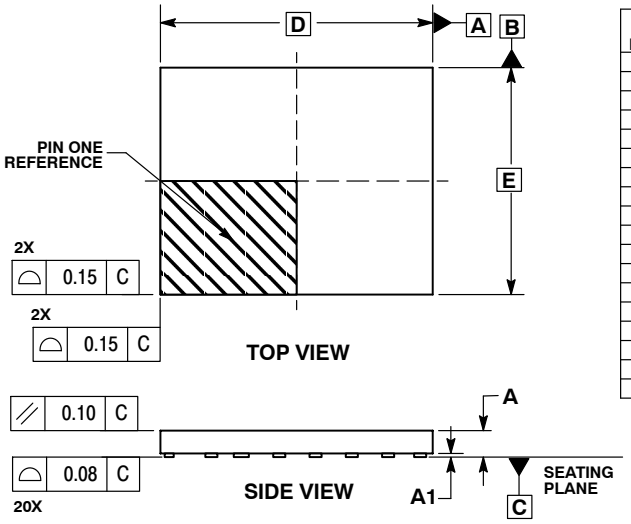
ON Semiconductor®

20 PIN LLGA, 6x5, 0.8P
CASE 513AC
ISSUE C

DATE 14 JAN 2014

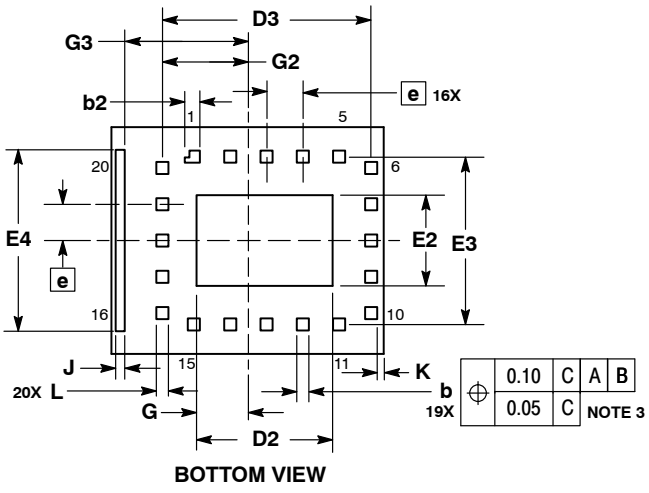


SCALE 2:1



DIM	MILLIMETERS MIN	MAX
A	0.50	0.60
A1	0.00	0.05
b	0.25	0.35
b2	0.35	0.45
D	6.00 BSC	
D2	2.90	3.10
D3	4.60 BSC	
E	5.00 BSC	
E2	1.90	2.10
E3	3.70 BSC	
E4	3.90	4.10
e	0.80 BSC	
G	1.05	1.25
G2	1.95 BSC	
G	2.55	2.75
J	0.15	0.25
K	0.10 MIN	
L	0.25	0.35

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



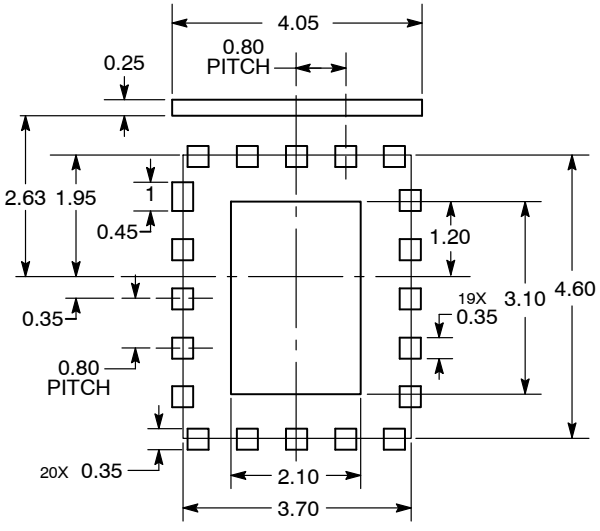
GENERIC MARKING DIAGRAM*

XXXX = Specific Device Code
A = Assembly Location
LL = Wafer Lot
YY = Year
WW = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

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DESCRIPTION:	**20 PIN LLGA, 6X5X0.5, 0.8P**	**PAGE 1 OF 1**